

# INITIAL PRODUCT/PROCESS CHANGE NOTIFICATION Generic Copy

#### 28-FEB-2003

SUBJECT: ON Semiconductor Initial Product/Process Change Notification #12755

TITLE: Additional Wafer Capacity for 60V N-CHANNEL TMOS at PHENITEC

**EFFECTIVE DATE: 28-Jun-2003** 

AFFECTED CHANGE CATEGORY: Subcontractor Fab Site

**AFFECTED PRODUCT DIVISION: MOS Power Products Div** 

ADDITIONAL RELIABILITY DATA: Available

Contact your local ON Semiconductor Sales Office or Keith Stapley <RXNN90@onsemi.com>

**SAMPLES:** Contact your local ON Semiconductor Sales Office or Spiro Zeffereys<FFMYGQ@onsemi.com>

# FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact Sales Office or Karen Wright < RD9130@onsemi.com>

#### DISCLAIMER:

Initial Product/Process Change Notification (IPCN) -First Notification distributed to customers. Distributed at least 120 days from the effective date of the change.

This is an 'early warning' about an upcoming change and contains general information regarding the change details and devices affected. It also contains at least a reliability qualification plan, but the actual qualification data will be identified in the Final Product/Process Change Notification (FPCN). This notification will be followed by a Final Product/Process Change Notification (FPCN) at least 60 days from effective date of change.

#### **DESCRIPTION AND PURPOSE:**

This is the initial notification announcing ON Semiconductor is adding wafer fabrication capacity for the 60V, N-Channel TMOS7 MOSFET Technology at Phenitec Semiconductor Corp. located in Okayama, Japan. The Phenitec facility has been producing Power MOSFET products for ON Semiconductor since 1999 and is a preferred supplier. Several existing technologies within ON Semiconductor's Power MOSFET portfolio are sourced from Phenitec, including lower voltage TMOS7 products. Final PCNs will be issued in two phases, Q2 2003, and Q3 2003, as device characterization data is completed.

Electrical performance and datasheet specifications will not change.

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### **QUALIFICATION PLAN:**

High Temperature Reverse Bias:

Ta=150DegC, Vgs=0V, Vds=80%Vdss rating, Duration=1008Hrs, 3 Lots, 80pcs/Lot

High Temperature Gate Bias:

Ta=150DegC, Vgs= 100%Vgss rating, Vds=0V, Duration=1008Hrs, 3 Lots, 80pcs/Lot

Intermittent Operating Life:

Ton= Toff= 2 minutes, delta Tj= 100DegC, Duration= 15000Cy, 3Lots,80pcs/Lot

Temperature Cycling:

Temperature extremes==150DegC/-65DegC, Dwell time= 15 minutes,

Duration = 1000Cy, 3 Lots, 80pcs/Lot

Autoclave Testing:

Temperature= 121DegC, Relative Humidity= 100%, Pressure= 15psi,

Duration= 96Hrs, 3 Lots, 80pcs/Lot

# AFFECTED DEVICE LIST (WITHOUT SPECIALS):

#### **PART**

NTB13N10

NTB13N10T4

NTB18N06

NTB18N06L

NTB18N06LT4

NTB18N06LT4G

NTB18N06T4

NTB22N06

NTB22N06L

NTB22N06LT4

NTB22N06T4

NTB27N06L

NTB27N06LT4

NTB30N06L

NTB30N06LT4

NTB30N20

NTB30N20T4

NTB35N15

NTB35N15T4

NTB45N06L

NTB45N06LT4

NTB52N10

NTB52N10T4

NTC18N06

NTC18N06TR

NTC18N06WP

NTC3055L104

NTC3055L104TR

NTC3055L104WP

NTD12N10

NTD12N10-001

NTD12N10T4

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NTD15N06

NTD15N06-001

NTD15N06L

NTD15N06L-001

NTD15N06LT4

NTD15N06T4

NTD18N06

NTD18N06-001

NTD18N06L

NTD18N06L-001

NTD18N06LT4

NTD18N06T4

NTD20N06L

NTD20N06L-001

NTD20N06LT4

NTD24N06L

NTD24N06L-001

NTD24N06LT4

NTD3055-094

NTD3055-094-1

NTD3055-094T4

NTD3055L104

NTD3055L104-001

NTD3055L104T4

NTD3055L170

NTD3055L170-001

NTD3055L170T4

NTD32N06L

NTD32N06L-001

NTD32N06LT4

NTF3055-100T1

NTF3055-100T3

NTF3055-100T3LF

NTF3055L108T1

NTF3055L108T3

NTF3055L108T3LF

NTF3055L175T1

NTF3055L175T3

NTF3055L175T3LF

NTP13N10

NTP18N06

NTP18N06L

NTP22N06

NTP22N06L

NTP27N06L

NTP30N06L

NTP30N20

NTP35N15

NTP45N06L

NTP52N10

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